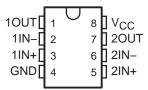
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- Single Supply or Dual Supplies
- Wide Range of Supply Voltage
 - Max Rating . . . 2 V to 36 V
 - Tested to 30 V . . . Non-V Devices
 - Tested to 32 V . . . V-Suffix Devices
- Low Supply-Current Drain Independent of Supply Voltage . . . 0.4 mA Typ Per Comparator
- Low Input Bias Current . . . 25 nA Typ
- Low Input Offset Current . . . 3 nA Typ (LM193)
- Low Input Offset Voltage . . . 2 mV Typ
- **Common-Mode Input Voltage Range Includes Ground**
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage . . . ±36 V
- **Low Output Saturation Voltage**
- Output Compatible With TTL, MOS, and **CMOS**

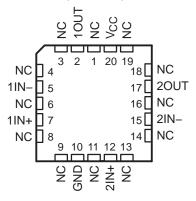
description/ordering information

These devices consist of two independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible as long as the difference between the two supplies is

LM193...D OR JG PACKAGE LM293...D, DGK, OR P PACKAGE LM293A . . . D OR DGK PACKAGE LM393, LM393A . . . D, DGK, P, PS, OR PW PACKAGE LM2903...D, DGK, P, PS, OR PW PACKAGE (TOP VIEW)







NC - No internal connection

2 V to 36 V, and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

The LM193 is characterized for operation from -55°C to 125°C. The LM293 and LM293A are characterized for operation from -25°C to 85°C. The LM393 and LM393A are characterized for operation from 0°C to 70°C. The LM2903 is characterized for operation from -40°C to 125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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description/ordering information (continued)

ORDERING INFORMATION

TA	V _{IOmax} AT 25°C	MAX V _{CC}	PACKAG	ΕŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
			PDIP (P)	Tube of 50	LM393P	LM393P
			COIC (D)	Tube of 75	LM393D	1.14202
			SOIC (D)	Reel of 2500	LM393DR	LM393
	5 mV	30 V	SOP (PS)	Reel of 2000	LM393PSR	L393
			TOOOD (DIA))	Tube of 150	LM393PW	1,000
			TSSOP (PW)	Reel of 2000	LM393PWR	L393
0°C to 70°C			MSOP/VSSOP (DGK)	Reel of 2500	LM393DGKR	M9_‡
			PDIP (P)	Tube of 50	LM393AP	LM393AP
	2 mV 30 V		0010 (D)	Tube of 75	LM393AD	1.84000.4
			SOIC (D)	Reel of 2500	LM393ADR	LM393A
	2 mv	30 V	SOP (PS)	Reel of 2000	LM393APSR	L393A
			TSSOP (PW)	Reel of 2000	LM393APWR	L393A
			MSOP/VSSOP (DGK)	Reel of 2500	LM393ADGKR	M8_‡
			PDIP (P)	Tube of 50	LM293P	LM293P
	5 \	20.1/	COIC (D)	Tube of 75	LM293D	LMOOD
-25°C to 85°C	5 mV	30 V	SOIC (D)	Reel of 2500	LM293DR	LM293
		MSOP/VSSOP (DGK)	Reel of 2500	LM293DGKR	MC_‡	
			COIC (D)	Tube of 75	LM293AD	1.140000.4
	2 mV	30 V	SOIC (D)	Reel of 2500	LM293ADR	LM293A
			MSOP/VSSOP (DGK)	Reel of 2500	LM293ADGKR	MD_‡
			PDIP (P)	Tube of 50	LM2903P	LM2903P
			COIC (D)	Tube of 75	LM2903D	LM2903
	7 \	30 V	SOIC (D)	Reel of 2500	LM2903DR	LIVI2903
	7 mV	30 V	SOP (PS)	Reel of 2000	LM2903PSR	L2903
4000 to 40500			TSSOP (PW)	Reel of 2000	LM2903PWR	L2903
–40°C to 125°C			MSOP/VSSOP (DGK)	Reel of 2500	LM2903DGKR	MA_‡
	7 mV	32 V	SOIC (D)	Reel of 2500	LM2903VQDR	L2903V
	/ 1111	32 V	TSSOP (PW)	Reel of 2000	LM2903VQPWR	L2903V
	2>/	20.1/	SOIC (D)	Reel of 2500	LM2903AVQDR	L2903AV
	2 mV	32 V	TSSOP (PW)	Reel of 2000	LM2903AVQPWR	L2903AV
			CDIP (JG)	Tube of 50	LM193JG	LM193JG
–55°C to 125°C	5 mV	30 V	LCCC (FK)	Tube of 55	LM193FK	LM193FK
			SOIC (D)	Reel of 2500	LM193DR	LM193

TPackage drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



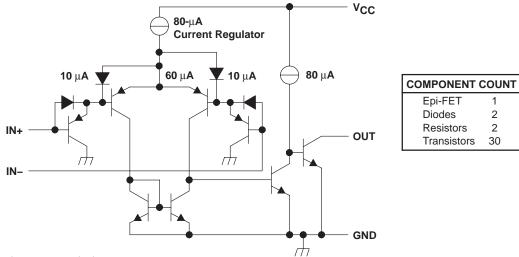
[‡] The actual top-side marking has one additional character that designates the assembly/test site.

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symbol (each comparator)



schematic (each comparator)



Current values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)		36 V
Differential input voltage, V _{ID} (see Note 2)		±36 V
Input voltage range, V _I (either input)		0.3 V to 36 V
Output voltage, V _O		
Output current, IO		20 mA
Duration of output short-circuit to ground (see Note 3)		Unlimited
Package thermal impedance, θ_{JA} (see Notes 4 and 5):	D package	97°C/W
	DGK package	172°C/W
	P package	85°C/W
	PS package	95°C/W
	PW package	149°C/W
Package thermal impedance, θ_{JC} (see Notes 6 and 7):	: FK package	5.61°C/W
	JG package	14.5°C/W
Operating virtual junction temperature, T _J		150°C
Case temperature for 60 seconds: FK package		260°C
Lead temperature 1,6 mm (1/16 inch) from case for 60	seconds: JG package	300°C
Storage temperature range, T _{stq}		_65°C to 150°C
9		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to GND.
 - 2. Differential voltages are at IN+, with respect to IN-.
 - 3. Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
 - Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 5. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 6. Maximum power dissipation is a function of $T_J(max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(max) T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - $7. \ \ \, \text{The package thermal impedance is calculated in accordance with MIL-STD-883}.$



LM193, LM293, LM293A LM393, LM393A, LM2903, LM2903V DUAL DIFFERENTIAL COMPARATORS

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electrical characteristics at specified free-air temperature, $V_{CC} = 5 \text{ V}$ (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONS	T _A †	LI	M193			M293 M393		UNIT
				,	MIN	TYP	MAX	MIN	TYP	MAX	
,,	land offertual to a	V _{CC} = 5 V to 30) V,	25°C		2	5		2	5	\/
V _{IO}	Input offset voltage	$V_O = 1.4 \text{ V},$ $V_{IC} = V_{IC(min)}$		Full range			9			9	mV
1	Input offset current	V 1 4 V		25°C		3	25		5	50	nA
lio	input onset current	V _O = 1.4 V		Full range			100			250	IIA
	lancet bina accument	V- 4.4V		25°C		-25	-100		-25	-250	^
IB	Input bias current	$V_0 = 1.4 \text{ V}$		Full range			-300			-400	nA
	Common-mode			25°C	0 to V _{CC} – 1.5	;		0 to V _{CC} – 1.5	i		.,
VICR	input voltage range‡			Full range	0 to V _{CC} – 2			0 to V _{CC} – 2			V
AVD	Large-signal differential-voltage amplification	V_{CC} = 15 V, V_{O} = 1.4 V to 1 $R_{L} \ge$ 15 kΩ to V		25°C	50	200		50	200		V/mV
	High-level	$V_{OH} = 5 V$,	V _{ID} = 1 V	25°C		0.1			0.1	50	nA
ЮН	output current	V _{OH} = 30 V,	V _{ID} = 1 V	Full range			1			1	μΑ
,,	Low-level	1 4 4		25°C		150	400		150	400	>/
VOL	output voltage	$I_{OL} = 4 \text{ mA},$	$V_{ID} = -1 V$	Full range			700			700	mV
lOL	Low-level output current	V _{OL} = 1.5 V,	V _{ID} = -1 V	25°C	6			6			mA
laa	Cupply ourrant	D	V _{CC} = 5 V	25°C		0.8	1		0.8	1	m 1
Icc	Supply current	R _L = ∞	V _C C = 30 V	Full range			2.5			2.5	mA

T Full range (MIN or MAX) for LM193 is -55°C to 125°C, for LM293 is 25°C to 85°C, and for LM393 is 0°C to 70°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.



[‡] The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC}+ – 1.5 V for the inverting input (–), and the non-inverting input (+) can exceed the V_{CC} level; the comparator provides a proper output state. Either or both inputs can go to 30 V without damage.

electrical characteristics at specified free-air temperature, $V_{CC} = 5 \text{ V}$ (unless otherwise noted)

	PARAMETER	TEST CONDITIO	NS	T _A †		//293A //393A		UNIT
					MIN	TYP	MAX	
\/	lanut affact valtage	$V_{CC} = 5 \text{ V to } 30 \text{ V}, V_{O} = 1.4 \text{ V},$		25°C		1	2	\/
VIO	Input offset voltage	$V_{IC} = V_{IC}(min)$		Full range			4	mV
	least effect comment	V 44V		25°C		5	50	- 4
lio	Input offset current	V _O = 1.4 V		Full range			150	nA
	Leave the second	V 44V		25°C		-25	-250	- 4
lΒ	Input bias current	V _O = 1.4 V		Full range			-400	nA
	Common-mode input voltage			25°C	0 to V _{CC} – 1.5	5		,,
VICR	range§			Full range	0 to V _{CC} – 2			V
A _{VD}	Large-signal differential-voltage amplification	$V_{CC} = 15 \text{ V}, V_{O} = 1.4 \text{ V to } 11.4 \text{ R}_{L} \ge 15 \text{ k}\Omega \text{ to } V_{CC}$	V,	25°C	50	200		V/mV
	I Pale Torrel and and account	V _{OH} = 5 V,	V _{ID} = 1 V	25°C		0.1	50	nA
ІОН	High-level output current	V _{OH} = 30 V,	V _{ID} = 1 V	Full range			1	μΑ
.,	Law L	1 4 4		25°C		150	400	
VOL	Low-level output voltage	$I_{OL} = 4 \text{ mA},$	$V_{ID} = -1 V$	Full range			700	mV
loL	Low-level output current	V _{OL} = 1.5 V,	$V_{ID} = -1 V$	25°C	6			mA
loo	Cupply ourront	D	V _{CC} = 5 V	25°C		0.8	1	mA
ICC	Supply current	R _L = ∞	V _{CC} = 30 V	Full range			2.5	IIIA

[†] Full range (MIN or MAX) for LM293A is 25°C to 85°C, and for LM393A is 0°C to 70°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.



[§] The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V, but either or both inputs can go to 30 V without damage.

LM193, LM293, LM293A LM393, LM393A, LM2903, LM2903V **DUAL DIFFERENTIAL COMPARATORS**

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electrical characteristics at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

	DADAMETED		VIDITION O	_ +	L	M2903		LM			
	PARAMETER	TEST CO	NDITIONS	T _A †	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	lanut effect valteres	$V_{CC} = 5 \text{ V to N}$	IAX‡,	25°C		2	7		1	2	mV
VIO	Input offset voltage	$V_O = 1.4 \text{ V},$ $V_{IC} = V_{IC(min)}$		Full range			15			4	mv
1	Innut offeet ourrent	V- 4.4.V		25°C		5	50		5	50	~ ^
lio	Input offset current	V _O = 1.4 V		Full range			200			200	nA
	lanut bina aumant	\/- 4 4\/		25°C		-25	-250		-25	-250	A
lΒ	Input bias current	V _O = 1.4 V		Full range			-500			-500	nA
,,	Common-mode			25°C	0 to V _{CC} – 1.	5		0 to V _{CC} – 1.5			.,
VICR	input voltage range§			Full range	0 to V _{CC} - 2			0 to V _{CC} – 2			V
A _{VD}	Large-signal differential-voltage amplification	$V_{CC} = 15 \text{ V},$ $V_{O} = 1.4 \text{ V to 1}$ $R_{L} \ge 15 \text{ k}\Omega \text{ to } \text{ V}$		25°C	25	100		25	100		V/mV
	High-level	V _{OH} = 5 V,	V _{ID} = 1 V	25°C		0.1	50		0.1	50	nA
ЮН	output current	VOH = VCC M/	4X, V _{ID} = 1 V	Full range			1			1	μΑ
.,	Low-level	1 4 55 4		25°C		150	400		150	400	>/
VOL	output voltage	$I_{OL} = 4 \text{ mA},$	$V_{ID} = -1 V$	Full range			700			700	mV
loL	Low-level output current	V _{OL} = 1.5 V,	V _{ID} = -1 V	25°C	6			6			mA
la a	Cumply ourrent	D.	V _{CC} = 5 V	25°C		0.8	1		0.8	1	A
Icc	Supply current	R _L = ∞	V _{CC} = MAX	Full range			2.5			2.5	mA

T Full range (MIN or MAX) for LM2903 is -40°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CO	NDITIONS	LM193 LM293, LM293A LM393, LM393A LM2903	UNIT
		100 11: 11: 11:		
Response time	R _L connected to 5 V through 5.1 k Ω ,	100-mV input step with 5-mV overdrive	1.3	แร
ixesponse time	C _L = 15 pF¶, See Note 8	TTL-level input step	0.3	μδ

[¶]C_L includes probe and jig capacitance.

NOTE 8: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.



[‡] V_{CC} MAX = 30 V for non-V devices and 32 V for V-suffix devices. § The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V, but either or both inputs can go to 30 V (32 V for V-suffix devices) without damage.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9452601Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9452601QPA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/11202BPA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
LM193DR	ACTIVE	SOIC	D	8	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
LM193DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM193FKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
LM193JG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
LM193JGB	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
LM2903AVQDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
LM2903AVQDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903AVQPWR	ACTIVE	TSSOP	PW	8	2000	TBD	CU NIPDAU	Level-1-250C-UNLIM
LM2903AVQPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903AVQPWRG4Q1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM2903PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM2903PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903PSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903PWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
LM2903PWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903PWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903PWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM





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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
LM2903QD	NRND	SOIC	D	8	75	TBD	CU NIPDAU	Level-1-220C-UNLIM
LM2903QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903QDR	NRND	SOIC	D	8	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM
LM2903QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903QP	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI
LM2903VQDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAF Level-1-235C-UNLIM
LM2903VQDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903VQPWR	ACTIVE	TSSOP	PW	8	2000	TBD	CU NIPDAU	Level-1-250C-UNLIM
LM2903VQPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM2903VQPWRG4Q1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293ADE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293ADG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293ADGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293ADGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293ADRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293ADRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM293P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type





com 13-May-2008

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽
LM293PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM393AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM393ADE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM393ADG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
LM393ADGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
LM393ADGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
LM393ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
LM393ADRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
LM393ADRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
LM393AP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM393APE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM393APSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
LM393APSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
LM393APSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
LM393APWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
LM393APWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLII
LM393APWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
LM393APWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
LM393D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
LM393DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
LM393DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLII
LM393DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
LM393DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLII
LM393DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLII
LM393DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLII
LM393DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLII





.com 13-May-2008

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³
LM393P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM393PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM393PSLE	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI
LM393PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM393PSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM393PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM393PWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM393PWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM393PWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
LM393PWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM393PWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN
LM393PWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

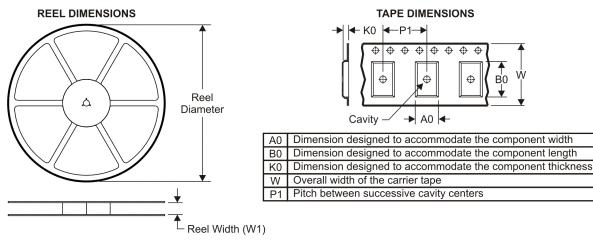
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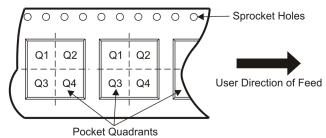


6-Jun-2008

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

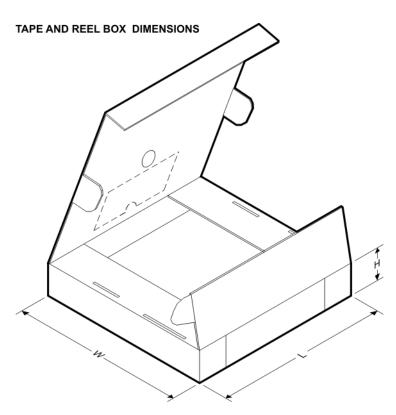
*All dimensions are nominal	1	1			1			1		1	1	1
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	(mm)	Pin1 Quadrant
LM2903DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.3	1.3	8.0	12.0	Q1
LM2903DGKR	MSOP	DGK	8	2500	330.0	13.0	5.3	3.4	1.4	8.0	12.0	Q1
LM2903DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM2903PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM293ADGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.3	1.3	8.0	12.0	Q1
LM293ADGKR	MSOP	DGK	8	2500	330.0	13.0	5.3	3.4	1.4	8.0	12.0	Q1
LM293ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.3	1.3	8.0	12.0	Q1
LM293DGKR	MSOP	DGK	8	2500	330.0	13.0	5.3	3.4	1.4	8.0	12.0	Q1
LM293DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADGKR	MSOP	DGK	8	2500	330.0	13.0	5.3	3.4	1.4	8.0	12.0	Q1
LM393ADGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.3	1.3	8.0	12.0	Q1
LM393ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1





i.com 6-Jun-2008

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM393APSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM393APWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM393DGKR	MSOP	DGK	8	2500	330.0	13.0	5.3	3.4	1.4	8.0	12.0	Q1
LM393DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.3	1.3	8.0	12.0	Q1
LM393DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM393PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2903DGKR	MSOP	DGK	8	2500	370.0	355.0	55.0
LM2903DGKR	MSOP	DGK	8	2500	358.0	335.0	35.0
LM2903DR	SOIC	D	8	2500	346.0	346.0	29.0
LM2903DR	SOIC	D	8	2500	340.5	338.1	20.6
LM2903PSR	SO	PS	8	2000	346.0	346.0	33.0
LM2903PWR	TSSOP	PW	8	2000	346.0	346.0	29.0
LM293ADGKR	MSOP	DGK	8	2500	370.0	355.0	55.0
LM293ADGKR	MSOP	DGK	8	2500	358.0	335.0	35.0
LM293ADR	SOIC	D	8	2500	340.5	338.1	20.6



PACKAGE MATERIALS INFORMATION

6-Jun-2008

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM293ADR	SOIC	D	8	2500	346.0	346.0	29.0
LM293DGKR	MSOP	DGK	8	2500	370.0	355.0	55.0
LM293DGKR	MSOP	DGK	8	2500	358.0	335.0	35.0
LM293DR	SOIC	D	8	2500	340.5	338.1	20.6
LM293DR	SOIC	D	8	2500	346.0	346.0	29.0
LM393ADGKR	MSOP	DGK	8	2500	358.0	335.0	35.0
LM393ADGKR	MSOP	DGK	8	2500	370.0	355.0	55.0
LM393ADR	SOIC	D	8	2500	340.5	338.1	20.6
LM393ADR	SOIC	D	8	2500	346.0	346.0	29.0
LM393APSR	SO	PS	8	2000	346.0	346.0	33.0
LM393APWR	TSSOP	PW	8	2000	346.0	346.0	29.0
LM393DGKR	MSOP	DGK	8	2500	358.0	335.0	35.0
LM393DGKR	MSOP	DGK	8	2500	370.0	355.0	55.0
LM393DR	SOIC	D	8	2500	340.5	338.1	20.6
LM393DR	SOIC	D	8	2500	346.0	346.0	29.0
LM393PSR	SO	PS	8	2000	346.0	346.0	33.0
LM393PWR	TSSOP	PW	8	2000	346.0	346.0	29.0

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to $http://www.ti.com/sc/docs/package/pkg_info.htm$

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

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